



SSC8120GS9

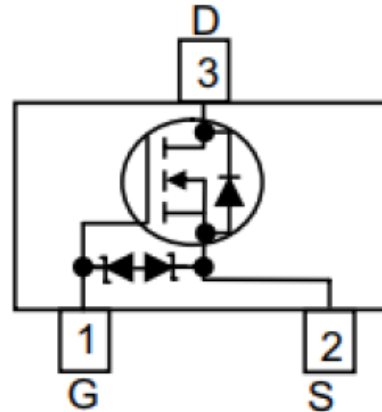
N-Channel Enhancement Mode MOSFET with ESD Protection

➤ Features

VDS	VGS	RDSON Typ	ID	ESD
20V	±12V	300mR@4V5	0.75A	1.2K
		440mR@2V5		
		800mR@1V8		

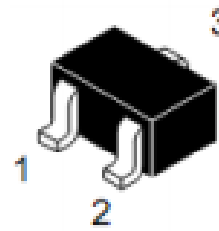
➤ Pin configuration

Top view



➤ Description

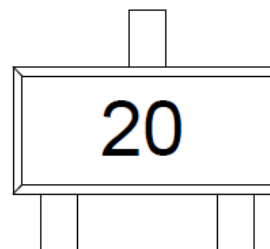
This device is a N-Channel enhancement mode MOSFET which is produced with high cell density and DMOS trench technology. This device particularly suits low voltage applications, especially for battery powered circuits, the tiny and thin outline saves PCB consumption.



SOT723

➤ Applications

- Replace Digital Transistor
- Battery Operated Systems
- Power Supply Converter Circuits
- Load/Power Switching cell Phones



Marking

➤ Ordering Information

Device	Package	Shipping
SSC8120GS9	SOT723	8000/Reel



➤ **Absolute Maximum Ratings**($T_A=25^{\circ}\text{C}$ unless otherwise noted)

Symbol	Parameter	Ratings	Unit
V_{DSS}	Drain-to-Source Voltage	20	V
V_{GSS}	Gate-to-Source Voltage	± 12	V
I_D	Continuous Drain Current	0.75	A
I_{DM}	Pulsed Drain Current	2	A
P_D	Power Dissipation	0.3	W
T_J	Operation junction temperature	-55 to 150	$^{\circ}\text{C}$
T_{STG}	Storage temperature range	-55 to 150	$^{\circ}\text{C}$

➤ **Thermal Resistance Ratings**($T_A=25^{\circ}\text{C}$ unless otherwise noted)

Symbol	Parameter	Typical	Maximum	Unit
$R_{\theta JA}$	Junction-to-Ambient Thermal Resistance		416	$^{\circ}\text{C}/\text{W}$
$R_{\theta JC}$	Junction-to-Case Thermal Resistance		266	

➤ **Electronics Characteristics**($T_A=25^{\circ}\text{C}$ unless otherwise noted)

Symbol	Parameter	Test Conditions	Min	Typ.	Max	Unit
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=250\mu\text{A}$	20			V
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=250\mu\text{A}$	0.35	0.6	1	V
$R_{DS(on)}$	Drain-Source On-Resistance	$V_{GS}=4.5V, I_D=0.6A$		300	450	mR
		$V_{GS}=2.5V, I_D=0.5A$		440	765	
		$V_{GS}=1.8V, I_D=0.35A$		800	1300	

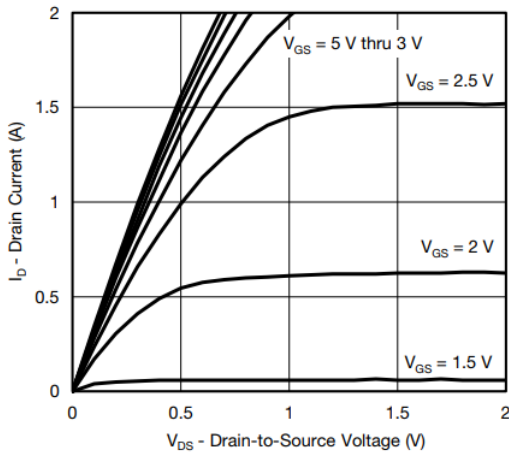


Symbol	Parameter	Test Conditions	Min	Typ.	Max	Unit
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS}=16V, V_{GS}=0V$			1	μA
I_{GSS}	Gate-Source leak current	$V_{GS}=\pm 12V, V_{DS}=0V$			± 10	μA
G_{FS}	Forward Transconductance	$V_{DS}=5V, I_D=0.5A$		11		S
V_{SD}	Forward Voltage	$V_{GS}=0V, I_S=0.15A$		0.7	1.3	V

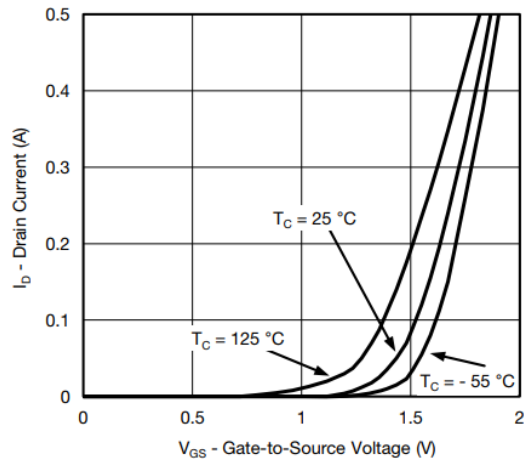
Symbol	Parameter	Test Conditions	Min	Typ.	Max	Unit
C_{iss}	Input Capacitance	$V_{DS}=16V, V_{GS}=0V,$ $F=200KHZ$		110		pF
C_{oss}	Output Capacitance			15		
C_{rss}	Reverse Transfer Capacitance			12		
$T_{D(ON)}$	Turn-on delay time	$V_{GEN}=4.5V,$ $V_{DS}=6V, R_G=6R,$ $R_L=6R, I_D=1A$			5	ns
$T_{D(OFF)}$	Turn-off delay time				26	



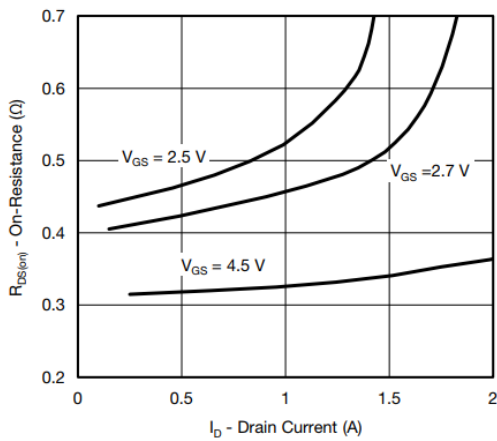
➤ **Typical Characteristics** ($T_A=25^\circ\text{C}$ unless otherwise noted)



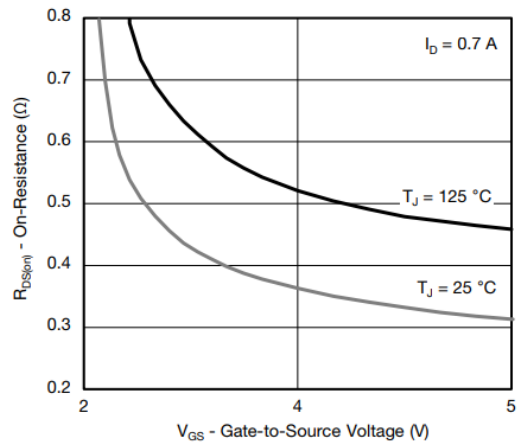
Output Characteristics



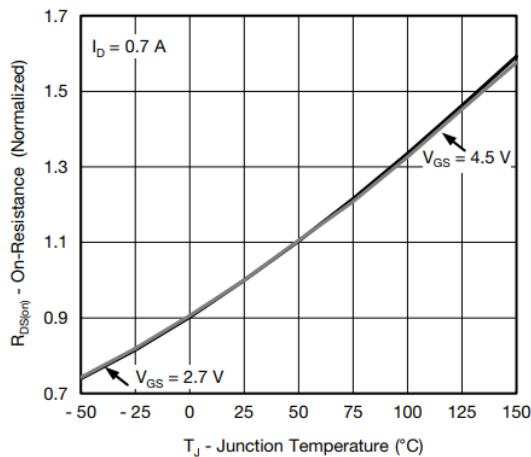
Transfer Characteristics



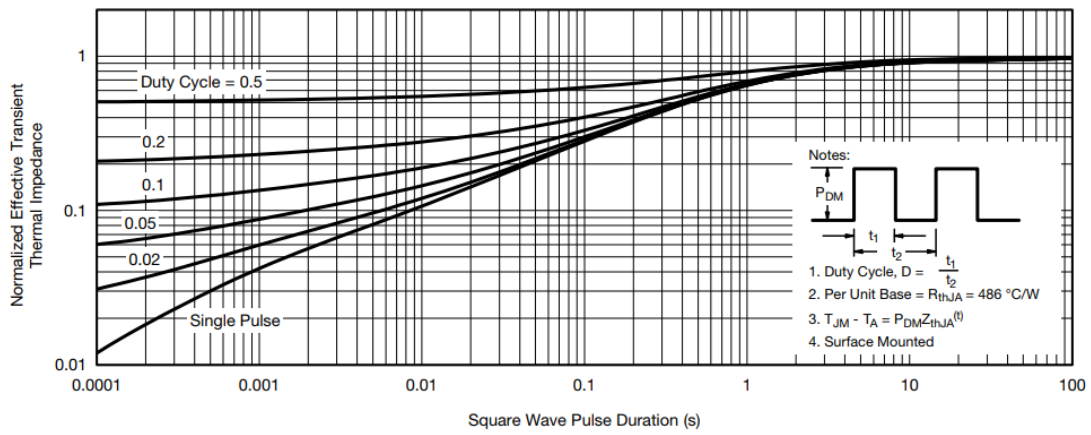
On-Resistance vs. Drain Current and Gate Voltage



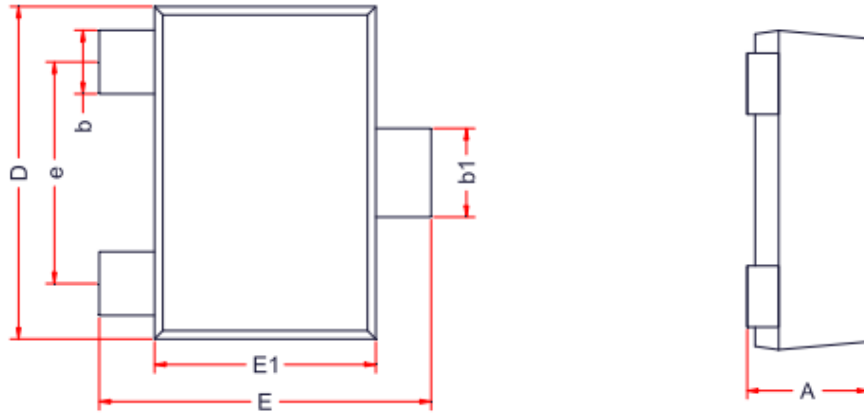
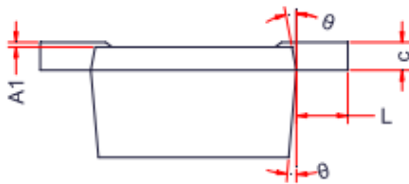
On-Resistance vs. Gate-to-Source Voltage



On-Resistance vs. Junction Temperature



Normalized Thermal Transient Impedance, Junction-to-Ambient

➤ Package Information
SOT-723

TOP VIEW
SIDE VIEW

SIDE VIEW

Symbol	Dimensions in Millimeters		
	Min.	Typ.	Max.
A	0.43	-	0.55
A1	0.00	-	0.05
c	0.08	0.13	0.18
b1	0.27	-	0.37
b	0.17	-	0.27
L1	0.15	0.20	0.25
D	1.15	1.20	1.25
E	1.15	1.20	1.25
E1	0.75	0.80	0.85
e	0.80 Ref.		
θ	7 ° Ref.		



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